

Product Specification

Product:	Conductive Platinum Paste, Sintered Platinum Paste
Part Number:	55H-1803D

Application Scope :

This product is suitable for high-temperature co-fired electrodes and sensor applications.

Usage Conditions :

Substrate	High temperature ceramic
Printing	200-300 mesh screen printing
Leveling	Let it level at room temperature for 5-15 minutes (adjust time based on actual leveling conditions).
Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (if the baking temperature is below 300°C, the baking time may be adjusted according to actual conditions).
Firing Condition	Sintering in an atmosphere of tunnel furnace air, with a peak temperature of 1100~1300°C (recommended value) for no less than 10 minutes. The maximum sintering temperature and heat resistance can reach 1400~1500°C.
Thinner	ST-1000

Characteristics :

1. Paste Characteristics :

Characteristic	Standard	Test Method And Conditions
1 Fineness	≤5μm	FOG test
2 Viscosity	120-280Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, 10 rpm, with adjustable viscosity at 25±1°C according to user requirements.

2. Characteristics After Curing :

Under the 1-sintering condition, the film thickness is 8-12 μm.

Check fired film produced under the conditions specified in 1) , (Film thickness is 8-12μm.)

Characteristics	Standard	Test Method And Conditions
3 Resistivity	≤50mΩ/□	Test pattern 0.6mm×60mm

4	Adhesion Strength		Peel Test: 0.5mmφ Tin plated Cu wire soldered on 2mm×2mm Pad. Solder: 96.5Sn/0.5Cu Mildly activated flux used.
	Initial Adhesion	≥45.2N	
	Ageing Adhesion	≥44.6N	Aging conditions: 150°C, 24 hours

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-25°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.